

L Number	Hits	Search Text	DB	Time stamp
1	41535	"ic chip" "integrated circuit chip"	USPAT; US-PGPUB	2004/04/17 14:32
2	105	("ic chip" "integrated circuit chip") with (coat\$ or film or layer) with thick\$4 with ("mu.m" or micron or micrometer or "micro meter" or nanometer or "nano meter" or angstrom)	USPAT; US-PGPUB	2004/04/17 14:35
3	132	("ic chip" "integrated circuit chip") with (coat\$ or film or layer) with thick\$4 with ("mu.m" or micron or micrometer or "micro meter" or nanometer or "nano meter" or angstrom)	USPAT; US-PGPUB	2004/04/17 14:53
4	13	"5936304"	USPAT; US-PGPUB	2004/04/17 14:51
5	15	("5084211"   "5245489"   "5583720"   "5936304"   "5995321"   "6042894"   "6134084"   "6166888"   "6268980"   "6282062"   "6339519"   "6344248"   "6369985"   "6437944"   "6522502").PN.	USPAT	2004/04/17 14:46
6	2	("5311059"   "5319242").PN.	USPAT	2004/04/17 14:50
7	34	"5274913"	USPAT; US-PGPUB	2004/04/17 14:53
8	4	("4143456"   "4323914"   "4942140"   "5120678").PN.	USPAT	2004/04/17 14:53
9	0	("ic chip" "integrated circuit chip") with (coat\$ or film or layer) with thick\$4 with ("mu.m" or micron or micrometer or "micro meter" or nanometer or "nano meter" or angstrom)	EPO; JPO; DERWENT; IBM_TDB	2004/04/17 14:53
10	12	("ic chip" or "integrated circuit chip") with (coat\$ or film or layer) with thick\$4 with ("mu.m" or micron or micrometer or "micro meter" or nanometer or "nano meter" or angstrom)	EPO; JPO; DERWENT; IBM_TDB	2004/04/17 14:55
11	652	("ic chip" or "integrated circuit chip") with (coat\$ or film or layer) near4 protect\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/17 15:09
12	391	@ad<19990528 and ((ic chip" or "integrated circuit chip") with (coat\$ or film or layer) near4 protect\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/17 15:17
13	108	@rlad<19990528 and ((ic chip" or "integrated circuit chip") with (coat\$ or film or layer) near4 protect\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/17 14:57

14	297	@pd<19990528 and ("ic chip" or "integrated circuit chip") with (coat\$ or film or layer) near4 protect\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/17 14:57
15	425	@ad<19990528 and ("ic chip" or "integrated circuit chip") with (coat\$ or film or layer) near4 protect\$4)) (@rlad<19990528 and ("ic chip" or "integrated circuit chip") with (coat\$ or film or layer) near4 protect\$4)) (@pd<19990528 and ("ic chip" or "integrated circuit chip") with (coat\$ or film or layer) near4 protect\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/17 15:05
16	0	polypylylene	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/17 15:05
17	0	"polyp xylylene"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/17 15:07
18	748	"poly p xylylene"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/17 15:06
19	288	"poly p xylene"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/17 15:06
20	1	"poly pxylene"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/17 15:06
21	0	"polypylylene"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/17 15:06
22	3	"poly pxylylene"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/17 15:07
23	1006	"poly p xylylene" "poly p xylene" "poly pxylene" "poly pxylylene"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/17 15:07

24	5	("poly p xylylene" "poly p xylene" "poly pxylene" "poly pxylylene") with (ic or chip or "integrated circuit")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/17 15:43
25	10430	(ic or chip or "integrated circuit") with (coat\$ or film or layer) near4 protect\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/17 15:15
26	5150	(ic or chip or "integrated circuit") with protective adj (coat\$ or film or layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/17 15:10
27	453	(ic or chip or "integrated circuit") with protecting adj (coat\$ or film or layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/17 15:10
28	5574	((ic or chip or "integrated circuit") with protective adj (coat\$ or film or layer)) ((ic or chip or "integrated circuit") with protecting adj (coat\$ or film or layer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/17 15:10
29	2836	(ic or chip or "integrated circuit") with protect\$4 adj (coat\$ or film or layer).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/17 15:11
30	2836	(ic or chip or "integrated circuit").ab. with protect\$4.ab. adj (coat\$ or film or layer).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/17 15:11
31	1013	(ic or chip or "integrated circuit") with protect\$4 with (coat\$ or film or layer) with thick\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/17 15:13
32	1594	("semiconductor chip") with protect\$4 near4 (coat\$ or film or layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/17 15:14
33	1594	("semiconductor chip") with (coat\$ or film or layer) near4 protect\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/17 15:15

34	6846	(ic or chip or "integrated circuit") with protect\$4 adj (coat\$ or film or layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/17 15:15
35	8166	(protect\$4 adj (coat\$ or film or layer)) with thickness with (micron or "mu.m" or micrometer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/17 15:16
36	8168	(protect\$4 adj (coat\$ or film or layer)) with thickness with (micron or "mu.m" or micrometer or "micro meter")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/17 15:17
37	334	((ic or chip or "integrated circuit") with protect\$4 adj (coat\$ or film or layer)) and ((protect\$4 adj (coat\$ or film or layer)) with thickness with (micron or "mu.m" or micrometer or "micro meter"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/17 15:17
38	162	@ad<19990528 and (((ic or chip or "integrated circuit") with protect\$4 adj (coat\$ or film or layer)) and ((protect\$4 adj (coat\$ or film or layer)) with thickness with (micron or "mu.m" or micrometer or "micro meter"))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/17 15:57
39	77	@rlad<19990528 and (((ic or chip or "integrated circuit") with protect\$4 adj (coat\$ or film or layer)) and ((protect\$4 adj (coat\$ or film or layer)) with thickness with (micron or "mu.m" or micrometer or "micro meter"))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/17 15:18
40	96	@pd<19990528 and (((ic or chip or "integrated circuit") with protect\$4 adj (coat\$ or film or layer)) and ((protect\$4 adj (coat\$ or film or layer)) with thickness with (micron or "mu.m" or micrometer or "micro meter"))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/17 15:18
41	193	(@ad<19990528 and (((ic or chip or "integrated circuit") with protect\$4 adj (coat\$ or film or layer)) and ((protect\$4 adj (coat\$ or film or layer)) with thickness with (micron or "mu.m" or micrometer or "micro meter")))) (@rlad<19990528 and (((ic or chip or "integrated circuit") with protect\$4 adj (coat\$ or film or layer)) and ((protect\$4 adj (coat\$ or film or layer)) with thickness with (micron or "mu.m" or micrometer or "micro meter")))) (@pd<19990528 and (((ic or chip or "integrated circuit") with protect\$4 adj (coat\$ or film or layer)) and ((protect\$4 adj (coat\$ or film or layer)) with thickness with (micron or "mu.m" or micrometer or "micro meter"))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/17 15:29

42	6	"11250602" "04047511"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/04/17 15:31
43	2	"11195202"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/04/17 15:31
44	2	5923501.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/04/17 15:33
45	9	("poly p xylylene" "poly p xylene" "poly pxylene" "poly pxylylene") with (ic or chip or "integrated circuit" or semiconductor or icc)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/04/17 15:44
46	32	("poly p xylylene" "poly p xylene" "poly pxylene" "poly pxylylene") same (ic or chip or "integrated circuit" or semiconductor or icc)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/04/17 15:51
47	31	5274913.URPN.	USPAT	2004/04/17 15:45
48	15	"348972"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/04/17 15:48
49	15	"62147735" "63065632" "01055832" "02084747"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/04/17 15:51
50	3868	parylene	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/04/17 15:51
51	735	parylene same (ic or chip or "integrated circuit" or semiconductor or icc)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/04/17 15:52
52	258	parylene with (ic or chip or "integrated circuit" or semiconductor or icc)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/04/17 15:54

53	164	<b>parylene with (ic or chip or "integrated circuit" or icc)</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	2004/04/17 15:55
54	10	<b>parylene with (ic or chip or "integrated circuit" or icc) with thick\$4</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	2004/04/17 15:56
55	435	<b>polymer\$5 with (ic or chip or "integrated circuit" or icc) with thick\$4</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	2004/04/17 15:56
56	173	<b>(polymer\$5 near3 (film or layer or coating)) with (ic or chip or "integrated circuit" or icc) with thick\$4</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	2004/04/17 15:57
57	101	<b>@ad&lt;19990528 and ((polymer\$5 near3 (film or layer or coating)) with (ic or chip or "integrated circuit" or icc) with thick\$4)</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	2004/04/17 15:57
58	42	<b>@rlad&lt;19990528 and ((polymer\$5 near3 (film or layer or coating)) with (ic or chip or "integrated circuit" or icc) with thick\$4)</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	2004/04/17 15:57
59	77	<b>@pd&lt;19990528 and ((polymer\$5 near3 (film or layer or coating)) with (ic or chip or "integrated circuit" or icc) with thick\$4)</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	2004/04/17 15:57
60	122	<b>(@ad&lt;19990528 and ((polymer\$5 near3 (film or layer or coating)) with (ic or chip or "integrated circuit" or icc) with thick\$4)) (@rlad&lt;19990528 and ((polymer\$5 near3 (film or layer or coating)) with (ic or chip or "integrated circuit" or icc) with thick\$4)) (@pd&lt;19990528 and ((polymer\$5 near3 (film or layer or coating)) with (ic or chip or "integrated circuit" or icc) with thick\$4))</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	2004/04/17 16:05
61	1	<b>"11313738"</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	2004/04/17 16:06
62	1	<b>1999JP-0313738</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	2004/04/17 16:07

63	787	HIROSE-A\$.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/04/17 16:07
64	251941	(ic or chip).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/04/17 16:07
65	15	HIROSE-A\$.in. and ((ic or chip).ti.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/04/17 16:07
66	3	("6134084"   "6144530"   "6252743").PN.	USPAT	2004/04/17 16:09